

## CONFERENCES IN 2008:

### NOVEMBER:

2nd Int'l **Symposium on Photonic Packaging**  
November 13, 2008; Munich, Germany  
[www.mcc-pr.de/photonics/site](http://www.mcc-pr.de/photonics/site)  
Contact: [photonics@mcc-pr.de](mailto:photonics@mcc-pr.de)

### DECEMBER:

9th **VLSI Packaging Workshop in Japan**  
December 1 - 2, 2008; Kyoto, Japan  
[vlsi-pkg-ws.org](http://vlsi-pkg-ws.org)  
Contact: Michitaka Kimura, Renesas Technology Corp,  
[kimura.michitaka@renesas.com](mailto:kimura.michitaka@renesas.com)

10th **Electronics Packaging Technology Conference** (EPTC 2008) [www.eptc-ieee.net](http://www.eptc-ieee.net)  
December 9-12, 2008; Singapore  
Contact: Dr. Tong Yan Tee, [tytee@amkor.com](mailto:tytee@amkor.com)

**Electrical Design of Advanced Packaging and Systems** (EDAPS 2008) [www.edaps2008.org](http://www.edaps2008.org)  
December 10-12, 2008 COEX Conference Center  
Seoul, Korea  
Contact: S.M Yang, [yangsm@ee.kaist.ac.kr](mailto:yangsm@ee.kaist.ac.kr) (Office:  
+82-42-869-5458)

2nd Int'l Conference on **Thermal issues in Emerging Technologies, Theory and Applications** (ThETA2)  
December 17-20, 2008 Cairo, Egypt  
[www.thetaconf.org](http://www.thetaconf.org)  
Contact: [thetaconf@gmail.com](mailto:thetaconf@gmail.com)

## CONFERENCES IN 2009:

### JANUARY:

2009 **European Systems Packaging Workshop** (ESPW) [www.semi-therm.org](http://www.semi-therm.org)  
February 2-4, 2009 Kinsale, Ireland  
Contact: Alan Mathewson, [alan.mathewson@tyndall.ie](mailto:alan.mathewson@tyndall.ie)

### FEBRUARY:

8th Annual **FLEXIBLE Electronics & Displays Conference & Exhibition** [www.flextech.org](http://www.flextech.org)  
February 2-5, 2009 Phoenix, AZ, USA  
Contact: Alan Mathewson, [events@usdc.org](mailto:events@usdc.org)

### MARCH:

2009 **Semiconductor Thermal Measurement and Management Symposium** (SEMI-THERM 25)  
[www.semi-therm.org](http://www.semi-therm.org)  
March 15-19, 2009 San Jose, CA USA  
Contact: Tom Tarter, [ttarter@ieee.org](mailto:ttarter@ieee.org)

### APRIL:

**Design, Test, Integration and Packaging of MEMS/MOEMS (DTIP)**  
[cmp.imag.fr/conferences/dtip/dtip2009](http://cmp.imag.fr/conferences/dtip/dtip2009)  
April 1-3, 2009 Rome, Italy  
Contact: Chantal Benis-Morel, [chantal.benis@imag.fr](mailto:chantal.benis@imag.fr)

**International Conference on Electronics Packaging (ICEP)** [www.jiep.or.jp/icep](http://www.jiep.or.jp/icep)  
April 14-16 Kyoto, Japan

10th Int'l **Conference on Thermal, Mechanical and Multiphysics Simulation and Experiments in Micro-Electronics and Micro-Systems** (EuroSimE 2009)  
[www.eurosime.org](http://www.eurosime.org)  
April 26-29 2009 Technical University of Delft, The Netherlands  
Contact: [eurosime@astefo.com](mailto:eurosime@astefo.com)

### MAY:

**Workshop on Signal Propagation on Interconnects** (SPI'09) [spi.univ-brest.fr](http://spi.univ-brest.fr)  
May 12-15, 2009 Hotel Sofitel, Strasbourg, France  
Abstracts due: February 7, 2009  
Contact: Denis Deschacht, [denis.deschacht@lirmm.fr](mailto:denis.deschacht@lirmm.fr)

59th **Electronic Components and Technology Conference** (ECTC 2009) [www.ectc.net](http://www.ectc.net)  
May 25-29, 2009 San Diego, CA USA  
Contact: Jean Trehwella, [jeanmh@us.ibm.com](mailto:jeanmh@us.ibm.com)

### JUNE:

**European Microelectronics and Packaging Conference & Exhibition** (EMPC 2009)  
[www.empc2009.org](http://www.empc2009.org)  
June 14-17, 2009 Rimini, Italy  
Abstracts due: December 31, 2008  
Contact: Pragma Congressi, [segreteria@empc2009.org](mailto:segreteria@empc2009.org)

IEEE International Workshop on **Advances in Sensors and Interfaces** (IWASI'09) [iwasi.poliba.it](http://iwasi.poliba.it)  
June 25-26, 2009 Trani, Italy  
Papers due: February 28, 2009  
Contact: Prof. Daniela De Venuto, [d.devenuto@poliba.it](mailto:d.devenuto@poliba.it)

### SEPTEMBER:

2009 **IEEE Holm Conference on Electrical Contacts (Holm 2009)**  
[www.ewh.ieee.org/soc/cpmt/tc1/h2009/h2009top.html](http://www.ewh.ieee.org/soc/cpmt/tc1/h2009/h2009top.html)  
Sept. 14-16, 2009 Vancouver, BC, Canada  
Papers due: January 9, 2009  
Contact: April Coles, [a.coles@ieee.org](mailto:a.coles@ieee.org)

See the CPMT Society website for updates:

[www.cpmt.org/conf](http://www.cpmt.org/conf)